

542,278

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization International Bureau



(43) International Publication Date  
19 August 2004 (19.08.2004)

PCT

(10) International Publication Number  
WO 2004/070405 A1

(51) International Patent Classification<sup>7</sup>: G01R 31/28, H01L 21/66

(21) International Application Number: PCT/SG2003/000023

(22) International Filing Date: 5 February 2003 (05.02.2003)

(25) Filing Language: English

(26) Publication Language: English

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(81) Designated States (national): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

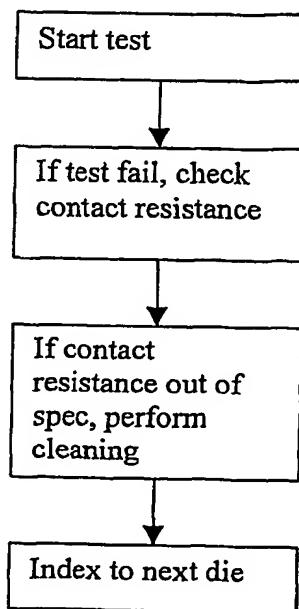
(84) Designated States (regional): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— with international search report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: PROBE CARD NEEDLE CLEANING FREQUENCY OPTIMIZATION



(57) Abstract: A system and method for optimizing cleaning of a probe card including using the probe card to test the functionality of dies on a wafer, when a die fails the probe test, and the probe reports failure to contact the pads of the die, checking the resistance of the probe needles, and if the resistance of a probe needle is greater than a predetermined value triggering probe needle cleaning.

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